



RB751S40

SURFACE MOUNT SCHOTTKY DIODES

VOLTAGE 40 Volts **CURRENT** 200 mA

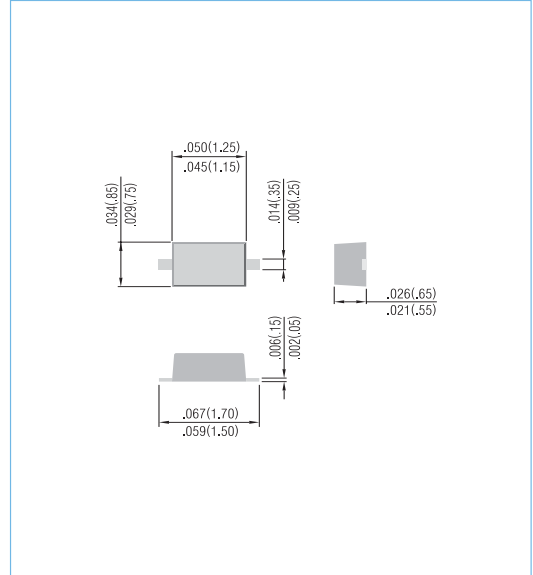
FEATURES

- Extremely Fast Switching Speed
- Very Low V_F : 0.325V (Typ) at $I_F = 1\text{mA}$
- Surface mount package ideally suited for automatic insertion
- Pb free product : 99% Sn above can meet Rohs environment substance directive request

MECHANICAL DATA

- Case: SOD-523, Plastic
- Terminals: Solderable per MIL-STD-750, Method 2026
- Appox Weight : 0.0014 gram
- Marking : 51

SOD-523 Unit: inch (mm)



ABSOLUTE RATINGS

PARAMETER	Symbol	Value	Units
Maximum Reverse DC Voltage	V_{RRM}	40	V
Peak Reverse Voltage	V_R	30	V
Maximum Forward Current	$I_{F(AV)}$	0.2	A
Power Dissipation ⁽¹⁾	P_{TOT}	0.2	A
Peak Forward Surge Current at t=8.3ms	I_{FSM}	500	mA
Junction Temperature	T_J	-55 to + 125	°C
Storage Temperature	T_{STG}	-55 to + 125	°C

THERMAL CHARACTERISTICS

PARAMETER	Symbol	Value	Units
Thermal Resistance, Junction to Ambient ⁽¹⁾	$R_{\theta JA}$	500	°C/W

1. FR-5 Board = 1.0 x 0.75 x 0.062 in. Minmum Pad Layout

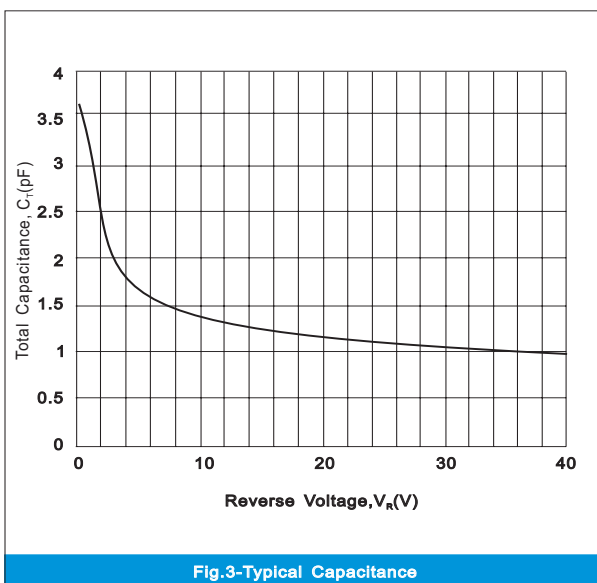
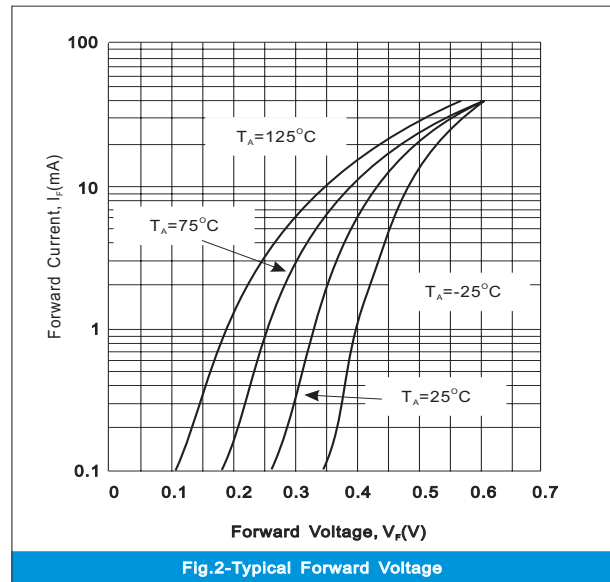
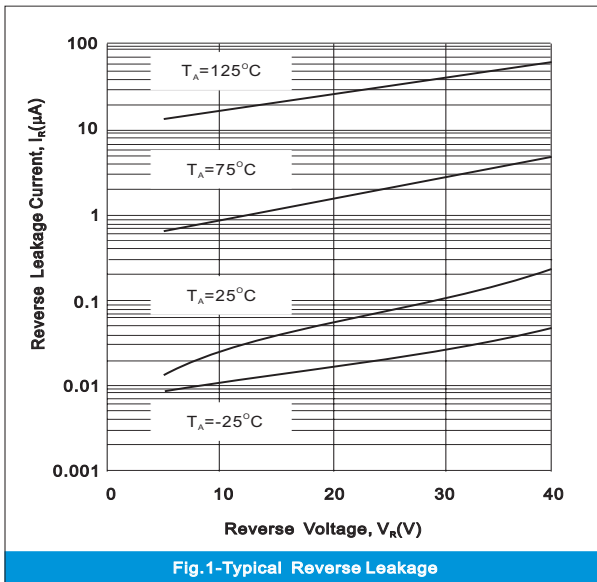


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ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

PARAMETER	Symbol	Test Condition	MIN.	TYP.	MAX.	Units
Reverse Leakage Current	I_R	$V_R=30\text{V}$	-	-	0.5	μA
Forward Voltage	V_F	$I_F=1\text{mA}$	-	-	0.37	V
Total Capacitance	C_T	$V_R=1\text{V}, F=1\text{MHz}$	-	3	5	pF

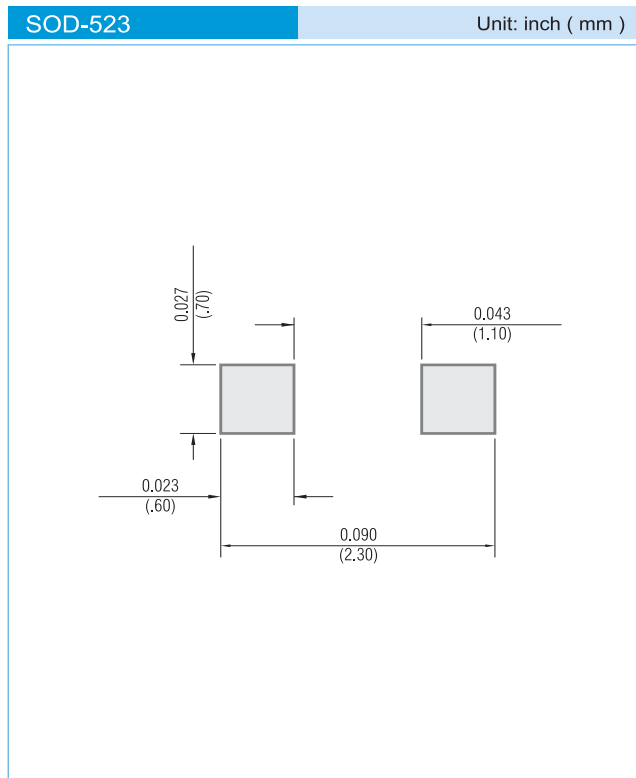
ELECTRICAL CHARACTERISTICS CURVE





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MOUNTING PAD LAYOUT



ORDER INFORMATION

- Packing information
 - T/R - 12K per 13" plastic Reel
 - T/R - 5K per 7" plastic Reel

LEGAL STATEMENT

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